

## LED 减薄砂轮

### Grinding Wheels for LED Substrate

Application: The grinding wheels for LED substrate are mainly used for back thinning of 2" , 4" and 6" LED epitaxial wafers. They can be used steadily on the Japanese, Korean and Taiwanese grinders with high performance.

应用领域: 用于 LED 行业衬底片和外延片的背减薄加工, 稳定配套日本、韩国、台湾主流研磨机, 可加工 2 寸、4 寸、6 寸外延片。砂轮主要性能已达到或超过进口同类产品水平。

Workpiece: sapphire epitaxial wafer, SiC substrate epitaxial wafer, Si substrate epitaxial wafer.

Material of workpiece: Synthetic sapphire, SiC ,single crystal silicon.

Grinders: WEC , GALAXY ,SPEEDFAM , NTS , SHUWA , OKAMOTO.

加工对象: 蓝宝石衬底外延片、SiC 衬底外延片、Si 衬底外延片等。

工件材料: 人造蓝宝石、SiC、单晶硅等。

配套研磨机: WEC、凯勒斯(GALAXY)、创技(SPEEDFAM)、NTS、SHUWA 冈本(OKAMOTO) 等。

Main Features:

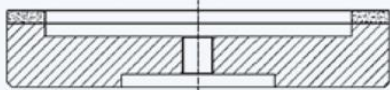

Good surface quality with high efficiency

No deep scratch and crash

Long life and low cost

主要特点：减薄效率高，表面质量好。砂轮质量稳定，不易深刮、碎片。砂轮寿命高，具有极高性价比，可大幅降低单片加工成本。

Specification 规格型号

形状代号 Shape code	剖面简图 Profile Sketch	配套机床 Grinder
6A2T		OKAMOTO
6A2T		
6A2T	